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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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HD74HC490

Dual 4-bit Decade Counters



ADE-205-507 (Z)

1st. Edition

Sep. 2000

Description

This circuit contains eight master-slave flip-flops and additional gating to implement two individual 4-bit decade counters. Each decade counter has individual clock, clear and set-to-9 inputs. BCD count sequences of any length up to divide-by-100 may be implemented with a single HD74HC490. Buffering on each output is provided to ensure that susceptibility to collector communication is reduced significantly. The counters have parallel outputs from each counter state so that submultiples of the input count frequency are available for system timing signals.

Features

- High Speed Operation: t_{pd} (Clock to Q_A) = 13 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

Function Table

Clear/Set-To-9

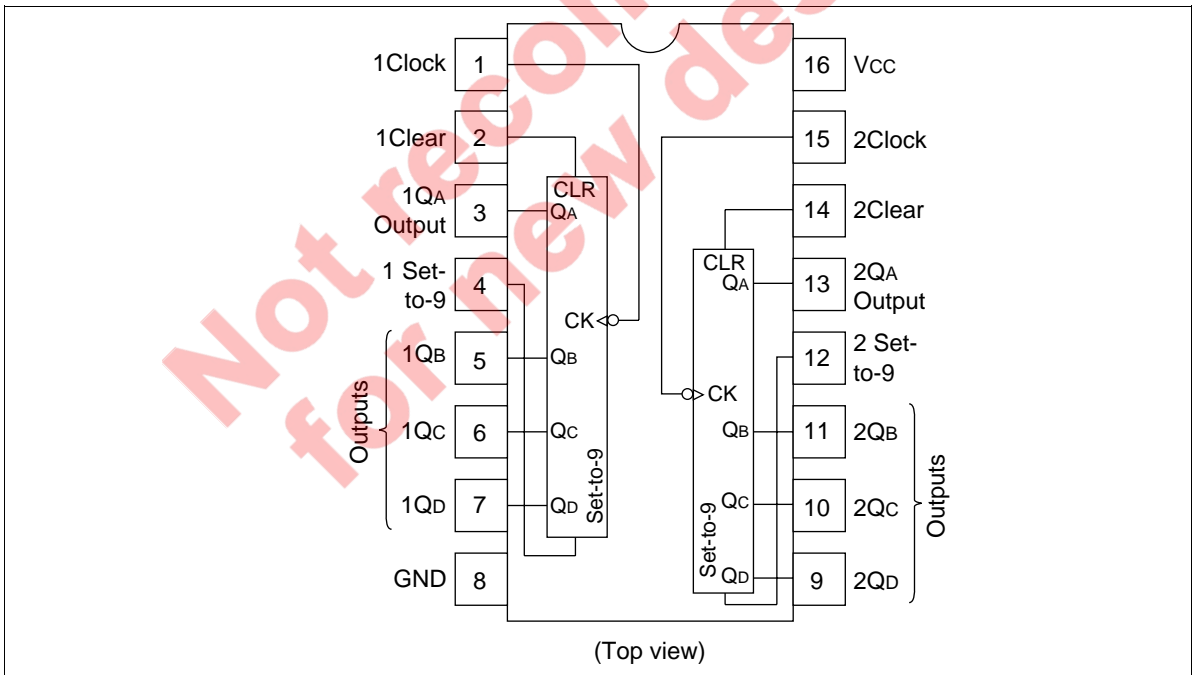
Inputs		Outputs			
Clear	Set-To-9	Q_A	Q_B	Q_C	Q_D
H	L	L	L	L	L
L	H	H	L	L	H
L	L	Count			

HD74HC490

BCD Count Sequence

Count	Outputs			
	Q _D	Q _C	Q _B	Q _A
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
5	L	H	L	H
6	L	H	H	L
7	L	H	H	H
8	H	L	L	L
9	H	L	L	H

Pin Arrangement



DC Characteristics

Item	Symbol	V _{CC} (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I _{OH} = -4 mA
		6.0	5.68	—	—	5.63	—			I _{OH} = -5.2 mA
		6.0	—	0.0	0.1	—	0.1			V
	V _{OL}	4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33		I _{OL} = 4 mA	
		6.0	—	—	0.26	—	0.33		I _{OL} = 5.2 mA	
		6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
		6.0	—	—	4.0	—	40	μA		Vin = V _{CC} or GND, I _{out} = 0 μA

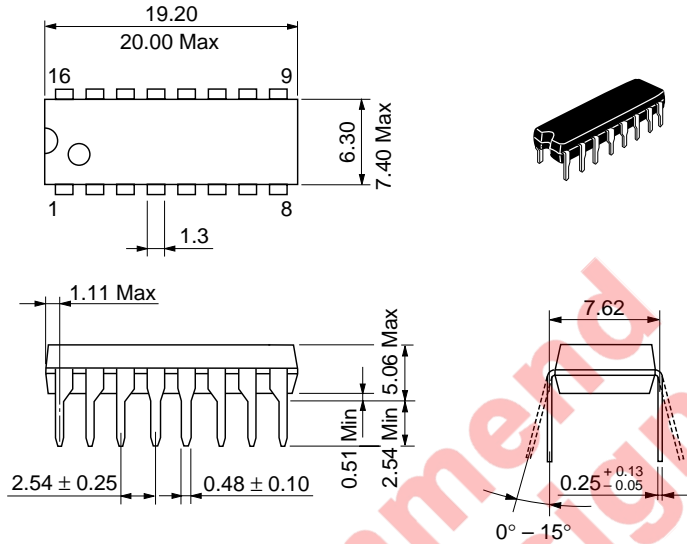
HD74HC490

AC Characteristics ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$		$T_a = -40$ to $+85^\circ\text{C}$		Unit	Test Conditions	
			Min	Typ	Max	Min			Max
Maximum clock frequency	f_{max}	2.0	—	—	4	—	3	MHz	
		4.5	—	—	20	—	16		
		6.0	—	—	24	—	19		
Propagation delay time	t_{PLH}	2.0	—	—	120	—	150	ns	Clock to Q_A
		4.5	—	13	24	—	30		
		6.0	—	—	20	—	26		
	t_{PHL}	2.0	—	—	205	—	255	ns	Clock to Q_B Q_C
		4.5	—	21	41	—	51		
		6.0	—	—	35	—	43		
	t_{PLH}	2.0	—	—	280	—	350	ns	Clock to Q_C
		4.5	—	23	56	—	70		
		6.0	—	—	48	—	60		
	t_{PHL}	2.0	—	—	205	—	255	ns	Clear to any output
		4.5	—	18	41	—	51		
		6.0	—	—	35	—	43		
	t_{PLH}	2.0	—	—	205	—	255	ns	Set-to-9 to Q_A , Q_D
		4.5	—	13	41	—	51		
		6.0	—	—	35	—	43		
	t_{PHL}	2.0	—	—	190	—	240	ns	Set-to-9 to Q_B , Q_C
		4.5	—	17	38	—	48		
		6.0	—	—	32	—	41		
Pulse width	t_w	2.0	80	—	—	100	—	ns	
		4.5	16	6	—	20	—		
		6.0	14	—	—	17	—		
Setup time	t_{su}	2.0	100	—	—	125	—	ns	
		4.5	20	1	—	25	—		
		6.0	17	—	—	21	—		
Output rise/fall time	t_{TLH}	2.0	—	—	75	—	95	ns	
		4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	C_{in}	—	—	5	10	—	10	pF	

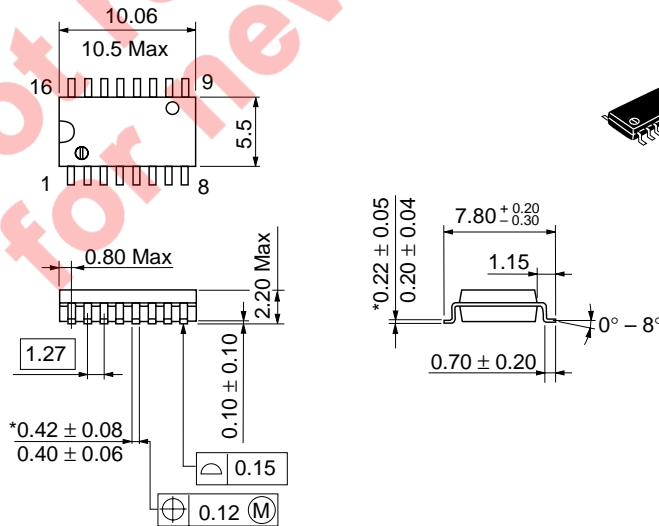
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

Unit: mm



Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

*Dimension including the plating thickness
Base material dimension

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HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica : <http://semiconductor.hitachi.com/>
 Europe : <http://www.hitachi-eu.com/hel/ecg>
 Asia : <http://sicapac.hitachi-asia.com>
 Japan : <http://www.hitachi.co.jp/Sicd/indx.htm>

For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe GmbH
Electronic Components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 585160

Hitachi Asia Ltd.
Hitachi Tower
16 Collyer Quay #20-00,
Singapore 049318
Tel : <65>-538-6533/538-8577
Fax : <65>-538-6933/538-3877
URL : <http://www.hitachi.com.sg>

Hitachi Asia Ltd.
(Taipei Branch Office)
4/F, No. 167, Tun Hwa North Road,
Hung-Kuo Building,
Taipei (105), Taiwan
Tel : <886>-(2)-2718-3666
Fax : <886>-(2)-2718-8180
Telex : 23222 HAS-TP
URL : <http://www.hitachi.com.tw>

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower,
World Finance Centre,
Harbour City, Canton Road
Tsim Sha Tsui, Kowloon,
Hong Kong
Tel : <852>-(2)-735-9218
Fax : <852>-(2)-730-0281
URL : <http://www.hitachi.com.hk>

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